

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUN ZENG	07/03/2014
MOHAMED N. DARWISH	07/01/2014
RICHARD A. BLANCHARD	07/01/2014
RECEIVING PARTY DATA	
Name:	MAXPOWER SEMICONDUCTOR, INC.
Street Address:	181 METRO DRIVE
Internal Address:	SUITE 590
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95110
PROPERTY NUMBERS Total: 3	
Property Type	Number
Application Number:	13175975
Application Number:	13770011
PCT Number:	US2011042914
CORRESPONDENCE DATA	
Fax Number:	(214)206-9992
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4695563578
Email:	ggroover@technopatents.com
Correspondent Name:	GWENDOLYN S.S. GROOVER
Address Line 1:	121 W. SOUTH COMMERCE ST.
Address Line 4:	WILLS POINT, TEXAS 75169
ATTORNEY DOCKET NUMBER:	MXP-052, -052A, -052WO
NAME OF SUBMITTER:	GWENDOLYN S.S. GROOVER
SIGNATURE:	/Gwendolyn S.S. Groover/
DATE SIGNED:	07/07/2014
Total Attachments: 5	
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ASSIGNMENT

As a below-named inventor of U.S. patent application 13/175,975 entitled "Power Semiconductor Devices, Structures, and Related Methods" (Atty Docket No. MXP-052), now issued as U.S. Patent 8,390,060; U.S. patent application 13/770,011 entitled "Power Semiconductor Devices, Structures, and Related Methods" (Atty Docket No. MXP-052A); and PCT patent application PCT/US11/42914 entitled "Power Semiconductor Devices, Structures, And Related Methods" (Atty Docket No. MXP-052WO), I hereby sell, assign and transfer to MaxPower Semiconductor, Inc., (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title, and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in the United States or any foreign country or national or regional patent authority, for the full term or terms of which the same may be granted, and specifically including the right to file international and foreign national or regional applications and claim priority to this application therefore under the provisions of any convention or treaty;

and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and I further hereby covenant that I will, upon ASSIGNEE'S request, promptly provide ASSIGNEE with all pertinent facts and documents, relating to said application, to any invention disclosed therein, or to any of said Letters Patent or legal equivalents thereof in the United States or in foreign countries, as may be known and accessible to me, and that I will testify and give evidence as to the same in any litigation or interference which may arise, and that I will promptly execute and deliver to ASSIGNEE or its legal representative, without charge but at Assignee's expense, any and all papers, instruments or affidavits which may be required, necessary or desirable for the purpose of applying for, obtaining, maintaining, issuing or enforcing said application and said Letters Patent and said equivalents thereof in the United States or in any foreign country; and I further authorize ASSIGNEE or its legal representative to make

any submissions or true declarations which may be needed in connection with the prosecution of this application or related applications in the U.S. or in other countries, consistent with the requirements of the applicable country;

AND I HEREBY AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign national or regional patent documents or grants related to this application and/or invention to ASSIGNEE, its successors and assigns.

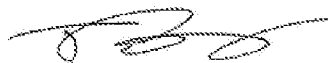
IN WITNESS WHEREOF, this Assignment has been executed on the date set forth below.

Inventor: Mohamed N. Darwish

Date: _____ Signature: _____

Residence: 675 Regas Dr, Campbell, CA 95008

Inventor: Jun Zeng

Date: __0703/2014_ Signature:  _____

Residence: 22495 Kent Ave, Torrance, CA 90505

Inventor: Richard A. Blanchard

Date: _____ Signature: _____

Residence: 10724 Mora Dr, Los Altos, CA 94024-6530

ASSIGNMENT

As a below-named inventor of U.S. patent application 13/175,975 entitled "Power Semiconductor Devices, Structures, and Related Methods" (Atty Docket No. MXP-052), now issued as U.S. Patent 8,390,060; U.S. patent application 13/770,011 entitled "Power Semiconductor Devices, Structures, and Related Methods" (Atty Docket No. MXP-052A); and PCT patent application PCT/US11/42914 entitled "Power Semiconductor Devices, Structures, And Related Methods" (Atty Docket No. MXP-052WO), I hereby sell, assign and transfer to MaxPower Semiconductor, Inc., (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title, and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in the United States or any foreign country or national or regional patent authority, for the full term or terms of which the same may be granted, and specifically including the right to file international and foreign national or regional applications and claim priority to this application therefore under the provisions of any convention or treaty;

and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and I further hereby covenant that I will, upon ASSIGNEE'S request, promptly provide ASSIGNEE with all pertinent facts and documents, relating to said application, to any invention disclosed therein, or to any of said Letters Patent or legal equivalents thereof in the United States or in foreign countries, as may be known and accessible to me, and that I will testify and give evidence as to the same in any litigation or interference which may arise, and that I will promptly execute and deliver to ASSIGNEE or its legal representative, without charge but at Assignee's expense, any and all papers, instruments or affidavits which may be required, necessary or desirable for the purpose of applying for, obtaining, maintaining, issuing or enforcing said application and said Letters Patent and said equivalents thereof in the United States or in any foreign country; and I further authorize ASSIGNEE or its legal representative to make

any submissions or true declarations which may be needed in connection with the prosecution of this application or related applications in the U.S. or in other countries, consistent with the requirements of the applicable country;

AND I HEREBY AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign national or regional patent documents or grants related to this application and/or invention to ASSIGNEE, its successors and assigns.

IN WITNESS WHEREOF, this Assignment has been executed on the date set forth below.

Inventor: Mohamed N. Darwish

Date: 7-1-2014 Signature: Mohamed N. Darwish

Residence: 675 Regas Dr, Campbell, CA 95008

Inventor: Jun Zeng

Date: _____ Signature: _____

Residence: 22495 Kent Ave, Torrance, CA 90505

Inventor: Richard A. Blanchard

Date: _____ Signature: _____

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Inventor: Mohamed N. Darwish

Date: _____ Signature: _____

Residence: 675 Regas Dr, Campbell, CA 95008

Inventor: Jun Zeng

Date: _____ Signature: _____

Residence: 22495 Kent Ave, Torrance, CA 90505

Inventor: Richard A. Blanchard

Date: July 1, 2014 Signature: Richard A. Blanchard

Residence: 10724 Mora Dr, Los Altos, CA 94024-6530